DISCRETE SEMICONDUCTORS

DATA SHEET

PDTA124T series PNP resistor-equipped transistors; R1 = 22 k Ω , R2 = open

Product specification Supersedes data of 2004 May 05 2004 Aug 04





PDTA124T series

FEATURES

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- · Inverter and interface circuits
- Circuit driver.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	_	-50	V
Io	output current (DC)	_	-100	mA
R1	bias resistor	22	_	kΩ
R2	open	_	_	_

DESCRIPTION

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

PRODUCT OVERVIEW

TYPE NUMBER	PACE	KAGE	MARKING CODE	NIDNI COMPLEMENT	
I TPE NUMBER	PHILIPS	EIAJ	MARKING CODE	NPN COMPLEMENT	
PDTA124TE	SOT416	SC-75	3R	PDTC124TE	
PDTA124TEF	SOT490	SC-89	24	PDTC124TEF	
PDTA124TK	SOT346	SC-59	59	PDTC124TK	
PDTA124TM	SOT883	SC-101	DJ	PDTC124TM	
PDTA124TS	SOT54 (TO-92)	SC-43	TA124T	PDTC124TS	
PDTA124TT	SOT23	-	*AE ⁽¹⁾	PDTC124TT	
PDTA124TU	SOT323	SC-70	*7B ⁽¹⁾	PDTC124TU	

Note

^{1. * =} p: Made in Hong Kong.

^{* =} t: Made in Malaysia.

^{* =} W: Made in China.

PNP resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTA124T series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL		PINNING
I TPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION
PDTA124TS	1 2 1 R1 3 3 MAM352	1 2 3	base collector emitter
PDTA124TE PDTA124TEF PDTA124TK PDTA124TT PDTA124TU	3 1 R1 3 Top view MDB272	1 2 3	base emitter collector
PDTA124TM	2 R1 3 1 Bottom view MDB268	1 2 3	base emitter collector

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PDTA124T series

ORDERING INFORMATION

TYPE		PACKAGE	
NUMBER NAME		DESCRIPTION	VERSION
PDTA124TE	_	plastic surface mounted package; 3 leads	SOT416
PDTA124TEF	_	plastic surface mounted package; 3 leads	SOT490
PDTA124TK	_	plastic surface mounted package; 3 leads	SOT346
PDTA124TM	_	leadless ultra small plastic package; 3 solder lands; body $1.0 \times 0.6 \times 0.5 \text{ mm}$	SOT883
PDTA124TS	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTA124TT	_	plastic surface mounted package; 3 leads	SOT23
PDTA124TU	_	plastic surface mounted package; 3 leads	SOT323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-50	V
V _{CEO}	collector-emitter voltage	open base	_	-50	V
V _{EBO}	emitter-base voltage	open collector	_	- 5	V
Io	output current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT23	note 1	_	250	mW
	SOT54	note 1	_	500	mW
	SOT323	note 1	_	200	mW
	SOT346	note 1	_	250	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air		
	SOT23	note 1	500	K/W
	SOT54	note 1	250	K/W
	SOT323	note 1	625	K/W
	SOT346	note 1	500	K/W
	SOT416	note 1	833	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0 \text{ A}$	_	_	-100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0 \text{ A}$	_	_	-1	μΑ
		$V_{CE} = -30 \text{ V}; I_{B} = 0 \text{ A};$ $T_{j} = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0 \text{ A}$	_	_	-100	nA
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -1 \text{ mA}$	100	_	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	_	-150	mV
R1	input resistor		15.4	22	28.6	kΩ
C _c	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = -10 \text{ V};$ f = 1 MHz	_	_	3	pF

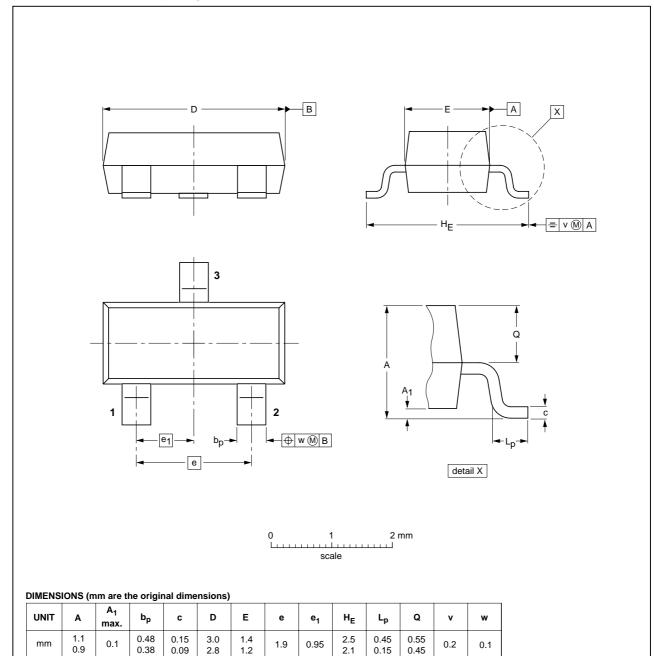
PNP resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTA124T series

PACKAGE OUTLINES

Plastic surface mounted package; 3 leads

SOT23



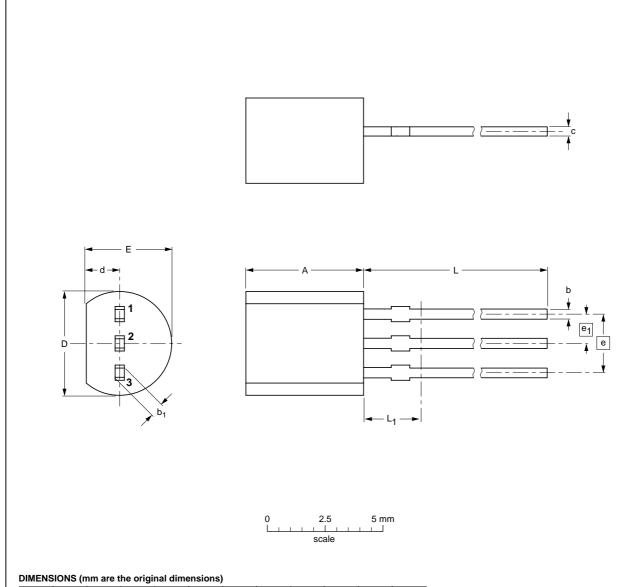
OUTLINE		REFERENCES EUROPEAN ISS				ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT23		TO-236AB				-97-02-28 99-09-13	

PNP resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTA124T series

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b ₁	С	D	d	E	е	e ₁	L	L ₁ ⁽¹⁾ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

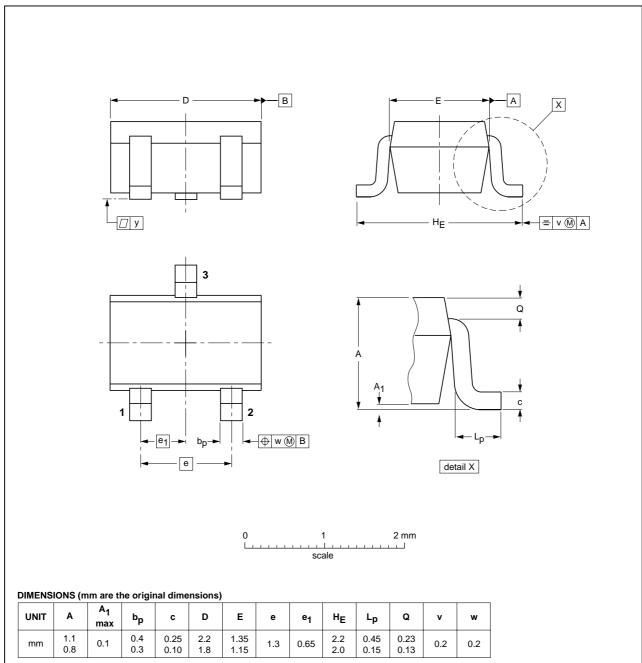
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VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43A		97-02-28 04-06-28	

PNP resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTA124T series

Plastic surface mounted package; 3 leads

SOT323

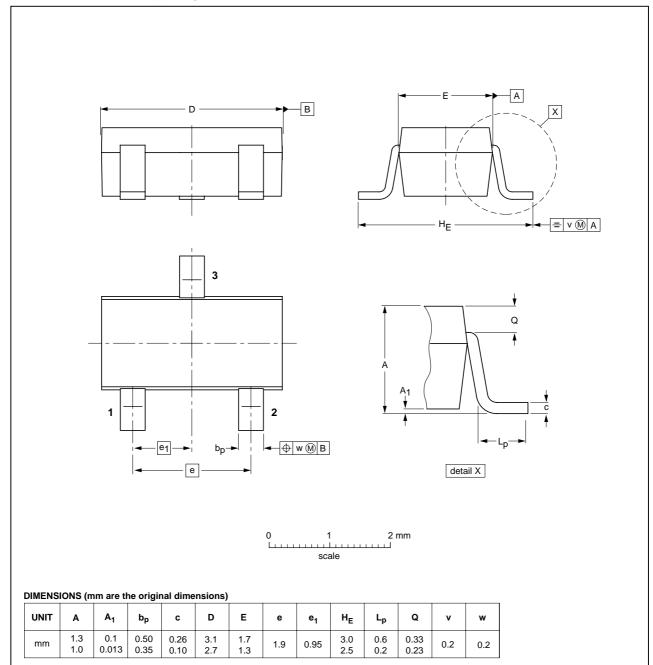


OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT323			SC-70		97-02-28

PDTA124T series

Plastic surface mounted package; 3 leads

SOT346

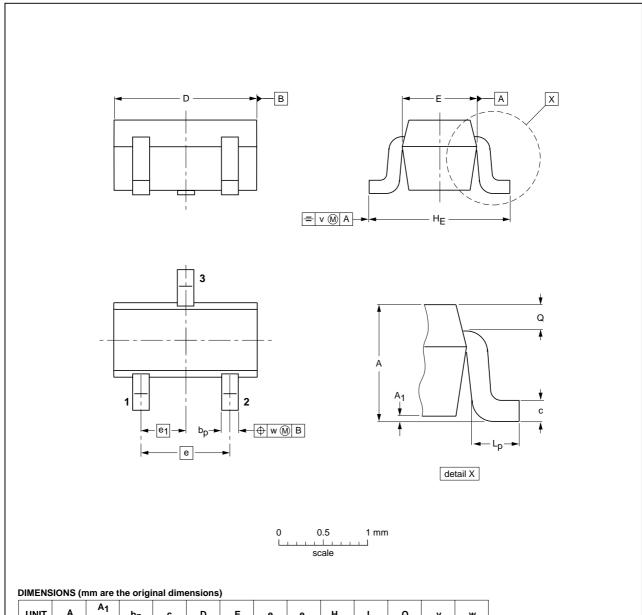


	REFER	ENCES	EUROPEAN	ISSUE DATE
IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
	TO-236	SC-59		98-07-17
	IEC	IEC JEDEC	IEC JEDEC EIAJ	IEC JEDEC EIAJ PROJECTION

PDTA124T series

Plastic surface mounted package; 3 leads

SOT416



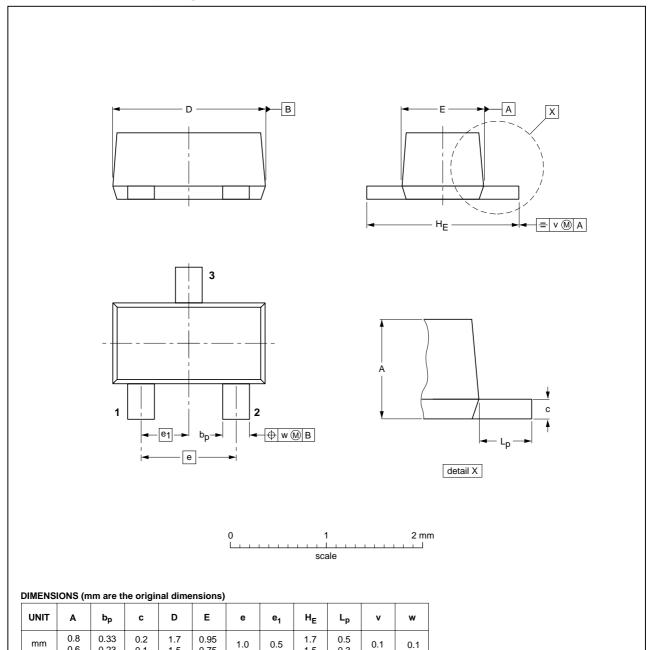
UNIT	A	A ₁ max	bp	С	D	E	e	e ₁	HE	Lp	Q	v	w
mm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	EUROPEAN	ICCUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT416			SC-75			97-02-28	

PDTA124T series

Plastic surface mounted package; 3 leads

SOT490



OUTLINE		REFER	EUROPEAN	ICCUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT490			SC-89			98-10-23	

2004 Aug 04 11

0.6

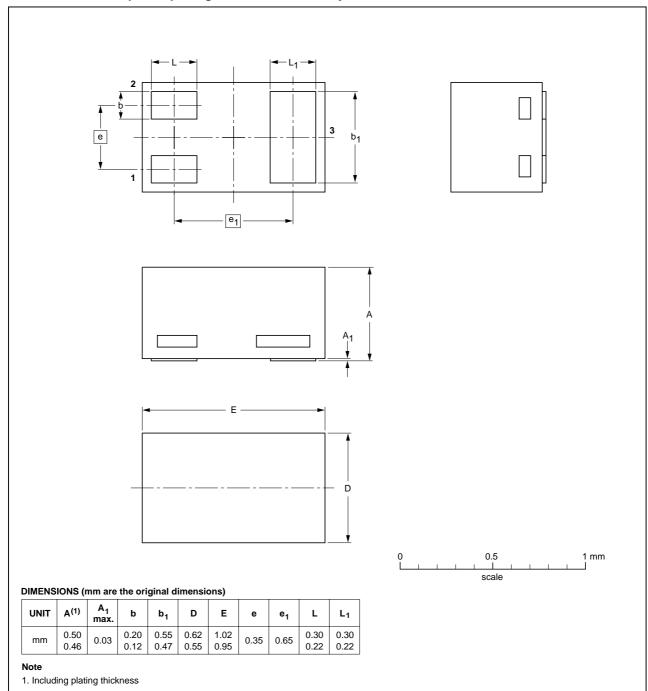
0.23

PNP resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTA124T series

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883



OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT883			SC-101			03-02-05 03-04-03	

PNP resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTA124T series

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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